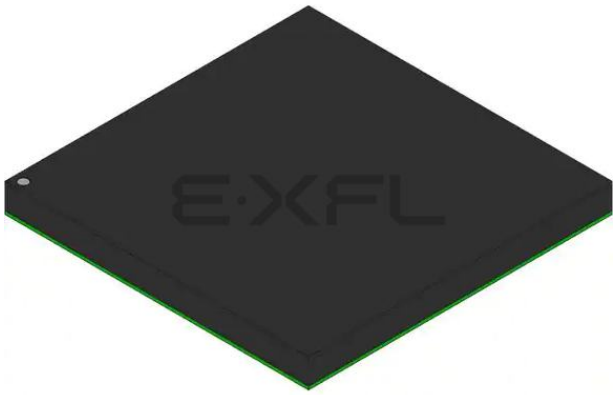

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

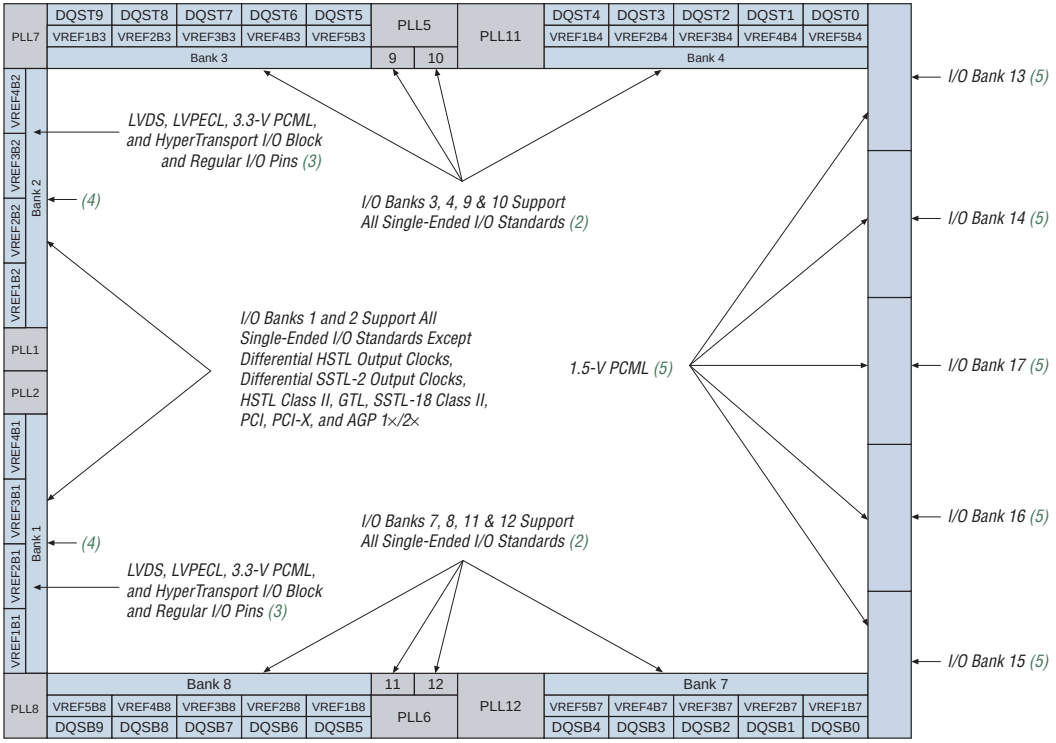
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	2566
Number of Logic Elements/Cells	25660
Total RAM Bits	1944576
Number of I/O	607
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-FBGA (33x33)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=ep1sgx25df1020c7

Figure 1–1. Stratix GX I/O Blocks *Note (1)*



Notes to Figure 1–1:

(1) Figure 1–1 is a top view of the Stratix GX silicon die.
(2) Banks 9 through 12 are enhanced PLL external clock output banks.
(3) If the high-speed differential I/O pins are not used for high-speed differential signaling, they can support all of the I/O standards except HSTL class I and II, GTL, SSTL-18 Class II, PCI, PCI-X, and AGP 1×/2×.
(4) For guidelines for placing single-ended I/O pads next to differential I/O pads, see the *Selectable I/O Standards in Stratix & Stratix GX Devices* chapter of the *Stratix GX Device Handbook, Volume 2*.
(5) These I/O banks in Stratix GX devices also support the LVDS, LVPECL, and 3.3-V PCML I/O standards on reference clocks and receiver input pins (AC coupled).

FPGA Functional Description

Stratix GX devices contain a two-dimensional row- and column-based architecture to implement custom logic. A series of column and row interconnects of varying length and speed provide signal interconnects between logic array blocks (LABs), memory block structures, and DSP blocks.

The transmitter PLL can support up to 3.1875 Mbps. The input clock frequency for –5 and –6 speed grade devices is limited to 650 MHz if you use the REFCLKB pin or to 325 MHz if you use the other clock routing resources. For –7 speed grade devices, the maximum input clock frequency is 312.5 MHz with the REFCLKB pin, and the maximum is 156.25 MHz for all other clock routing resources. An optional PLL_LOCKED port is available to indicate whether the transmitter PLL is locked to the reference clock. The transmitter PLL has a programmable loop bandwidth that can be set to low or high. The loop bandwidth parameter can be statically set in the Quartus II software.

Table 2–2 lists the adjustable parameters in the transmitter PLL.

Table 2–2. Transmitter PLL Specifications

Parameter	Specifications
Input reference frequency range	25 MHz to 650 MHz
Data rate support	500 Mbps to 3.1875 Gbps
Multiplication factor (W)	2, 4, 5, 8, 10, 16, or 20 *(1)*
Bandwidth	Low, high

Note to Table 2–2:
(1) Multiplication factors 2 and 5 can only be achieved with the use of the pre-divider on the REFCLKB pin.

Transmitter Phase Compensation FIFO Buffer

The transmitter phase compensation FIFO buffer resides in the transceiver block at the PLD boundary. This FIFO buffer compensates for the phase differences between the transmitter reference clock (inclk) and the PLD interface clock (tx_coreclk). The phase difference between the two clocks must be less than 360° . The PLD interface clock must also be frequency locked to the transmitter reference clock. The phase compensation FIFO buffer is four words deep and cannot be bypassed.

Byte Serializer

The byte serializer takes double-width words (16 or 20 bits) from the PLD interface and converts them to a single width word (8 or 10 bits) for use in the transceiver. The transmit data path after the byte serializer is single width (8 or 10 bits). The byte serializer is bypassed when single width mode (8 or 10 bits) is used at the PLD interface.

High-Speed Serial Bus Protocols

With wide, serial data rate range, Stratix GX devices can support multiple, high-speed serial bus protocols. Table 2–12 shows some of the protocols that Stratix GX devices can support.

Table 2–12. High-Speed Serial Bus Protocols

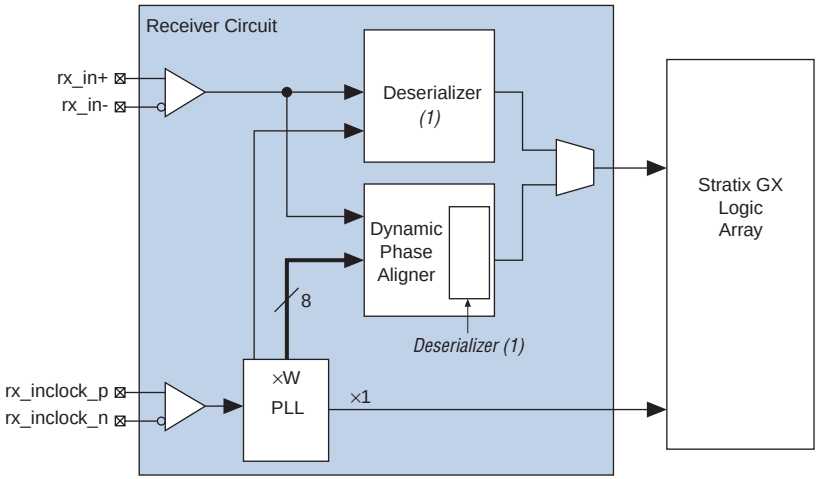
Bus Transfer Protocol	Stratix GX (Gbps) (Supports up to 3.1875 Gbps)
SONET backplane	2.488
10 Gigabit Ethernet XAUI	3.125
10 Gigabit fibre channel	3.1875
InfiniBand	2.5
Fibre channel (1G, 2G)	1.0625, 2.125
Serial RapidIO™	1.25, 2.5, 3.125
PCI Express	2.5
SMPTE 292M	1.485

DPA Block Overview

Each Stratix GX receiver channel features a DPA block. The block contains a dynamic phase selector for phase detection and selection, a SERDES, a synchronizer, and a data realigner circuit. You can bypass the dynamic phase aligner without affecting the basic source-synchronous operation of the channel by using a separate deserializer shown in Figure 3–5.

The dynamic phase aligner uses both the source clock and the serial data. The dynamic phase aligner automatically and continuously tracks fluctuations caused by system variations and self-adjusts to eliminate the phase skew between the multiplied clock and the serial data. Figure 3–5 shows the relationship between Stratix GX source-synchronous circuitry and the Stratix GX source-synchronous circuitry with DPA.

Figure 3–5. Source-Synchronous DPA Circuitry



Note to Figure 3–5:

(1) Both deserializers are identical. The deserializer operation is described in the "Principles of SERDES Operation" section.

TriMatrix Memory

TriMatrix memory consists of three types of RAM blocks: M512, M4K, and M-RAM blocks. Although these memory blocks are different, they can all implement various types of memory with or without parity, including true dual-port, simple dual-port, and single-port RAM, ROM, and FIFO buffers. Table 4–2 shows the size and features of the different RAM blocks.

Table 4–2. TriMatrix Memory Features (Part 1 of 2)

Memory Feature	M512 RAM Block (32 × 18 Bits)	M4K RAM Block (128 × 36 Bits)	M-RAM Block (4K × 144 Bits)
Maximum performance	*(1)*	*(1)*	*(1)*
True dual-port memory		✓	✓
Simple dual-port memory	✓	✓	✓
Single-port memory	✓	✓	✓
Shift register	✓	✓	
ROM	✓	✓	*(2)*
FIFO buffer	✓	✓	✓
Byte enable		✓	✓
Parity bits	✓	✓	✓
Mixed clock mode	✓	✓	✓
Memory initialization	✓	✓	
Simple dual-port memory mixed width support	✓	✓	✓
True dual-port memory mixed width support		✓	✓
Power-up conditions	Outputs cleared	Outputs cleared	Outputs unknown
Register clears	Input and output registers	Input and output registers	Output registers
Mixed-port read-during-write	Unknown output/old data	Unknown output/old data	Unknown output

or regional clock. In contrast, a circuit using asynchronous RAM must generate the RAM WREN signal while ensuring its data and address signals meet setup and hold time specifications relative to the WREN signal. The output registers can be bypassed. Flow-through reading is possible in the simple dual-port mode of M512 and M4K RAM blocks by clocking the read enable and read address registers on the negative clock edge and bypassing the output registers.

Two single-port memory blocks can be implemented in a single M4K block as long as each of the two independent block sizes is equal to or less than half of the M4K block size.

The Quartus II software automatically implements larger memory by combining multiple TriMatrix memory blocks. For example, two 256 × 16-bit RAM blocks can be combined to form a 256 × 32-bit RAM block. Memory performance does not degrade for memory blocks using the maximum number of words available in one memory block. Logical memory blocks using less than the maximum number of words use physical blocks in parallel, eliminating any external control logic that would increase delays. To create a larger high-speed memory block, the Quartus II software automatically combines memory blocks with LE control logic.

Parity Bit Support

The memory blocks support a parity bit for each byte. The parity bit, along with internal LE logic, can implement parity checking for error detection to ensure data integrity. You can also use parity-size data words to store user-specified control bits. In the M4K and M-RAM blocks, byte enables are also available for data input masking during write operations.

Shift Register Support

You can configure embedded memory blocks to implement shift registers for DSP applications such as pseudo-random number generators, multi-channel filtering, auto-correlation, and cross-correlation functions. These and other DSP applications require local data storage, traditionally implemented with standard flip-flops, which can quickly consume many logic cells and routing resources for large shift registers. A more efficient alternative is to use embedded memory as a shift register block, which saves logic cell and routing resources and provides a more efficient implementation with the dedicated circuitry.

The size of a $w \times m \times n$ shift register is determined by the input data width (w), the length of the taps (m), and the number of taps (n). The size of a $w \times m \times n$ shift register must be less than or equal to the maximum number of memory bits in the respective block: 576 bits for the M512

Table 4–8. M-RAM Block Configurations (True Dual-Port)				
Port A	Port B			
	64K × 9	32K × 18	16K × 36	8K × 72
64K × 9	✓	✓	✓	✓
32K × 18	✓	✓	✓	✓
16K × 36	✓	✓	✓	✓
8K × 72	✓	✓	✓	✓

The read and write operation of the memory is controlled by the WREN signal, which sets the ports into either read or write modes. There is no separate read enable (RE) signal.

Writing into RAM is controlled by both the WREN and byte enable (byteena) signals for each port. The default value for the byteena signal is high, in which case writing is controlled only by the WREN signal. The byte enables are available for the ×18, ×36, and ×72 modes. In the ×144 simple dual-port mode, the two sets of byteena signals (byteena_a and byteena_b) are combined to form the necessary 16 byte enables. Tables 4–9 and 4–10 summarize the byte selection.

Table 4–9. Byte Enable for M-RAM Blocks Notes (1), (2)			
byteena[3..0]	datain ×18	datain ×36	datain ×72
[0] = 1	[8..0]	[8..0]	[8..0]
[1] = 1	[17..9]	[17..9]	[17..9]
[2] = 1	–	[26..18]	[26..18]
[3] = 1	–	[35..27]	[35..27]
[4] = 1	–	–	[44..36]
[5] = 1	–	–	[53..45]
[6] = 1	–	–	[62..54]
[7] = 1	–	–	[71..63]

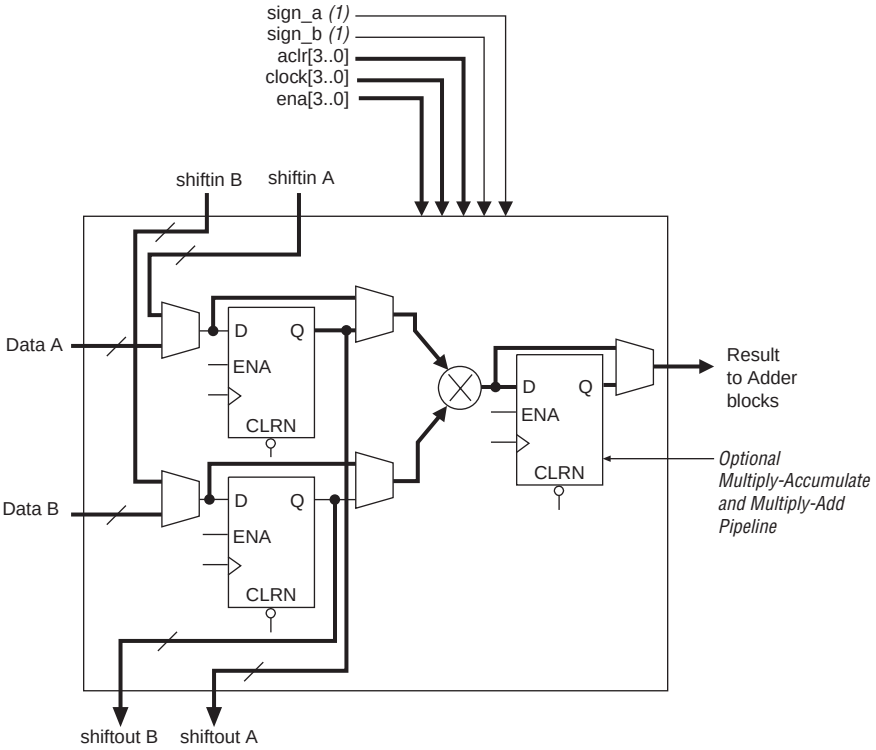
The DSP block consists of the following elements:

- Multiplier block
- Adder/output block

Multiplier Block

The DSP block multiplier block consists of the input registers, a multiplier, and pipeline register for pipelining multiply-accumulate and multiply-add/subtract functions as shown in Figure 4–31.

Figure 4–31. Multiplier Sub-Block Within Stratix GX DSP Block



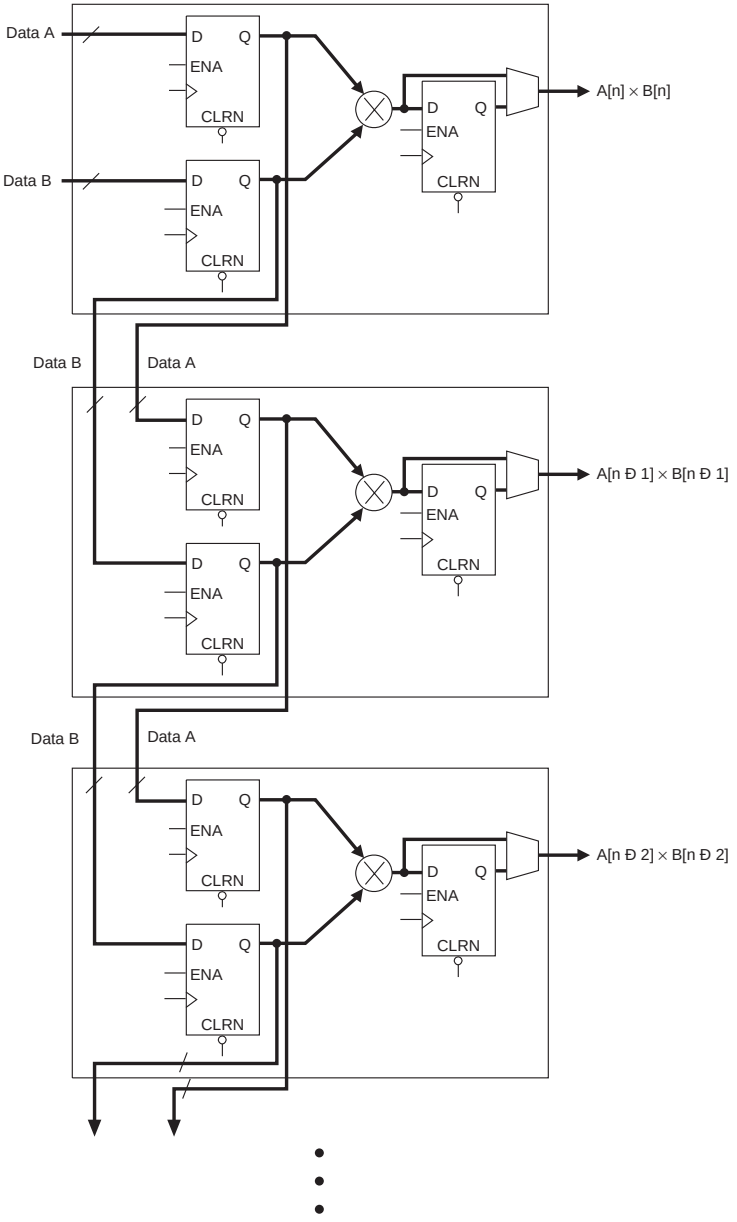
Note to Figure 4–31:
(1) These signals can be unregistered or registered once to match data path pipelines if required.

Input Registers

A bank of optional input registers is located at the input of each multiplier and multiplicand inputs to the multiplier. When these registers are configured for parallel data inputs, they are driven by regular routing resources. You can use a clock signal, asynchronous clear signal, and a clock enable signal to independently control each set of A and B inputs for each multiplier in the DSP block. You select these control signals from a set of four different `clock[3..0]`, `aclr[3..0]`, and `ena[3..0]` signals that drive the entire DSP block.

You can also configure the input registers for a shift register application. In this case, the input registers feed the multiplier and drive two dedicated shift output lines: `shiftoutA` and `shiftoutB`. The shift outputs of one multiplier block directly feed the adjacent multiplier block in the same DSP block (or the next DSP block) as shown in Figure 4–32, to form a shift register chain. This chain can terminate in any block, that is, you can create any length of shift register chain up to 224 registers. You can use the input shift registers for FIR filter applications. One set of shift inputs can provide data for a filter, and the other are coefficients that are optionally loaded in serial or parallel. When implementing 9 × 9- and 18 × 18-bit multipliers, you do not need to implement external shift registers in LAB LEs. You implement all the filter circuitry within the DSP block and its routing resources, saving LE and general routing resources for general logic. External registers are needed for shift register inputs when using 36 × 36-bit multipliers.

Figure 4–32. Multiplier Sub-Blocks Using Input Shift Register Connections *Note (1)*



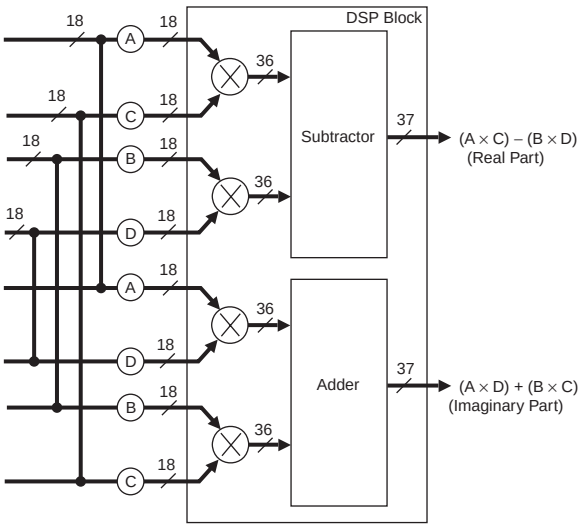
Note to Figure 4–32:
(1) Either Data A or Data B input can be set to a parallel input for constant coefficient multiplication.

You can use the two-multipliers adder mode for complex multiplications, which are written as:

$$(a + jb) \times (c + jd) = [(a \times c) - (b \times d)] + j \times [(a \times d) + (b \times c)]$$

The two-multipliers adder mode allows a single DSP block to calculate the real part $[(a \times c) - (b \times d)]$ using one subtractor and the imaginary part $[(a \times d) + (b \times c)]$ using one adder, for data widths up to 18 bits. Two complex multiplications are possible for data widths up to 9 bits using four adder/subtractor/accumulator blocks. Figure 4–37 shows an 18-bit two-multipliers adder.

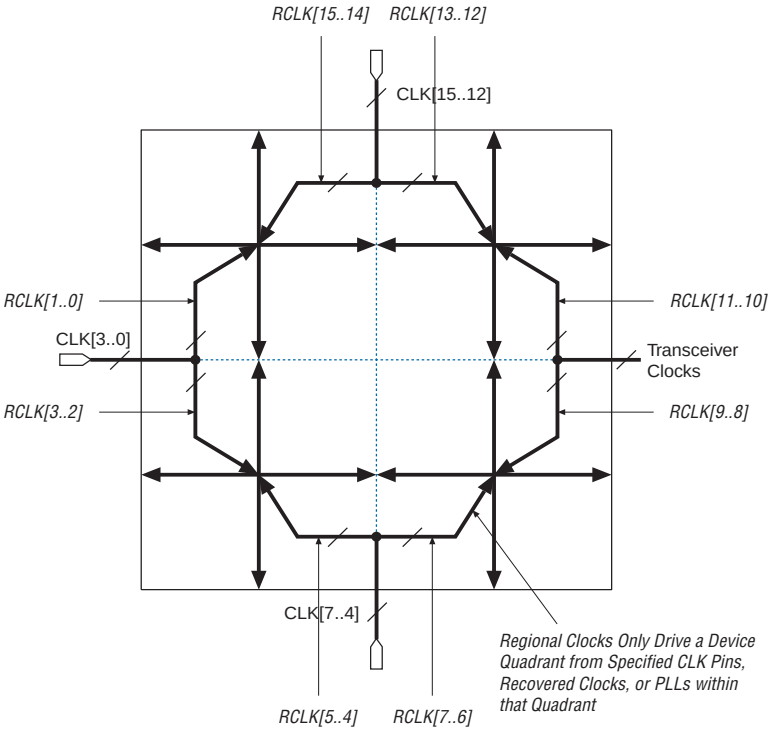
Figure 4–37. Two-Multipliers Adder Mode Implementing Complex Multiply



Four-Multipliers Adder Mode

In the four-multipliers adder mode, the DSP block adds the results of two first -stage adder/subtractor blocks. One sum of four 18 × 18-bit multipliers or two different sums of two sets of four 9 × 9-bit multipliers can be implemented in a single DSP block. The product width for each multiplier must be the same size. The four-multipliers adder mode is useful for FIR filter applications. Figure 4–38 shows the four multipliers adder mode.

Figure 4–42. Regional Clocks



Fast Regional Clock Network

In EP1SGX25 and EP1SGX10 devices, there are two fast regional clock networks, FCLK[1..0], within each quadrant, fed by input pins (see Figure 4–43). In EP1SGX40 devices, there are two fast regional clock networks within each half-quadrant (see Figure 4–44). The FCLK[1..0] clocks can also be used for high fanout control signals, such as asynchronous clears, presets, clock enables, or protocol control signals such as TRDY and IRDY for PCI. Dual-purpose FCLK pins drive the fast clock networks. All devices have eight FCLK pins to drive fast regional clock networks. Any I/O pin can drive a clock or control signal onto any fast regional clock network with the addition of a delay. The I/O interconnect drives this signal.

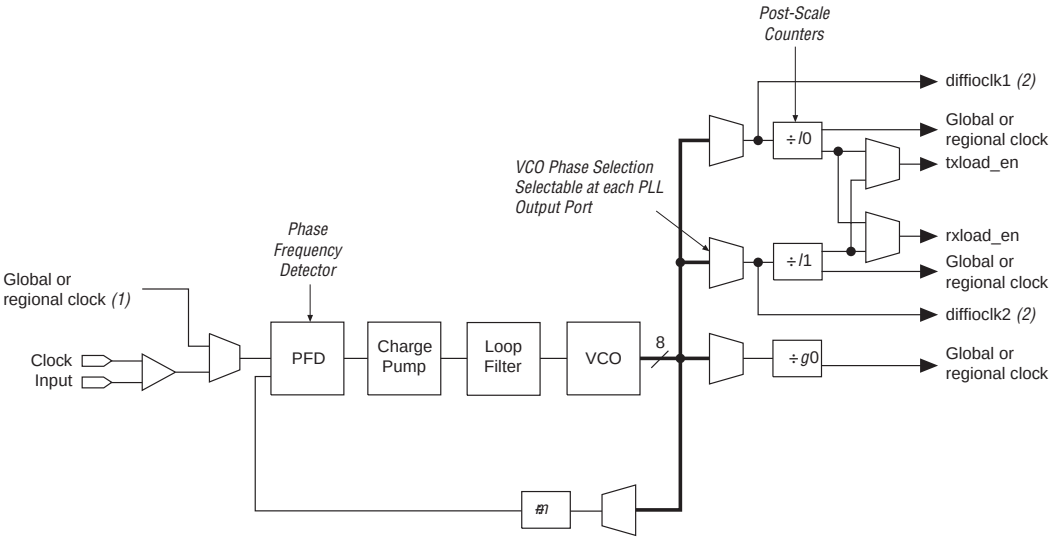
pair of output pins (four pins total) has dedicated VCC and GND pins to reduce the output clock's overall jitter by providing improved isolation from switching I/O pins.

For PLLs 5 and 6, each pin of a single-ended output pair can either be in phase or 180° out of phase. The clock output pin pairs support the same I/O standards as standard output pins (in the top and bottom banks) as well as LVDS, LVPECL, 3.3-V PCML, HyperTransport technology, differential HSTL, and differential SSTL. Table 4–19 shows which I/O standards the enhanced PLL clock pins support. When in single-ended or differential mode, the two outputs operate off the same power supply. Both outputs use the same standards in single-ended mode to maintain performance. You can also use the external clock output pins as user output pins if external enhanced PLL clocking is not needed.

Table 4–19. I/O Standards Supported for Enhanced PLL Pins (Part 1 of 2)

I/O Standard	Input			Output
	INCLK	FBIN	PLLENABLE	EXTCLK
LVTTL	✓	✓	✓	✓
LVCMOS	✓	✓	✓	✓
2.5 V	✓	✓		✓
1.8 V	✓	✓		✓
1.5 V	✓	✓		✓
3.3-V PCI	✓	✓		✓
3.3-V PCI-X	✓	✓		✓
LVPECL	✓	✓		✓
3.3-V PCML	✓	✓		✓
LVDS	✓	✓		✓
HyperTransport technology	✓	✓		✓
Differential HSTL	✓			✓
Differential SSTL				✓
3.3-V GTL	✓	✓		✓
3.3-V GTL+	✓	✓		✓
1.5-V HSTL class I	✓	✓		✓
1.5-V HSTL class II	✓	✓		✓
SSTL-18 class I	✓	✓		✓
SSTL-18 class II	✓	✓		✓
SSTL-2 class I	✓	✓		✓
SSTL-2 class II	✓	✓		✓

Figure 4–57. Stratix GX Device Fast PLL



Notes to Figure 4–57:

(1) In high-speed differential I/O support mode, this high-speed PLL clock feeds the SERDES. Stratix GX devices only support one rate of data transfer per fast PLL in high-speed differential I/O support mode.

(2) This signal is a high-speed differential I/O support SERDES control signal.

Clock Multiplication & Division

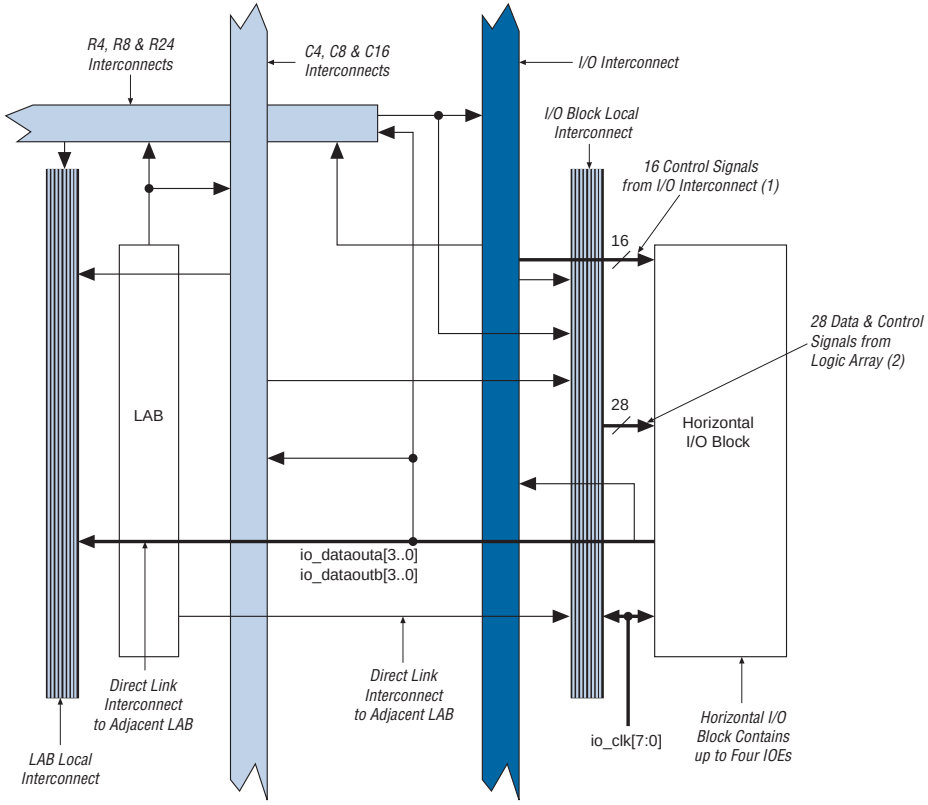
The Stratix GX device's fast PLLs provide clock synthesis for PLL output ports using *m*/(post scaler) scaling factors. The input clock is multiplied by the *m* feedback factor. Each output port has a unique post scale counter to divide down the high-frequency VCO. There is one multiply divider, *m*, per fast PLL with a range of 1 to 32. There are two post scale L dividers for regional and/or LVDS interface clocks, and *g*0 counter for global clock output port; all range from 1 to 32.

In the case of a high-speed differential interface, you can set the output counter to 1 to allow the high-speed VCO frequency to drive the SERDES.

External Clock Outputs

Each fast PLL supports differential or single-ended outputs for source-synchronous transmitters or for general-purpose external clocks. There are no dedicated external clock output pins. Any I/O pin can be driven by the fast PLL global or regional outputs as an external output

Figure 4–59. Row I/O Block Connection to the Interconnect



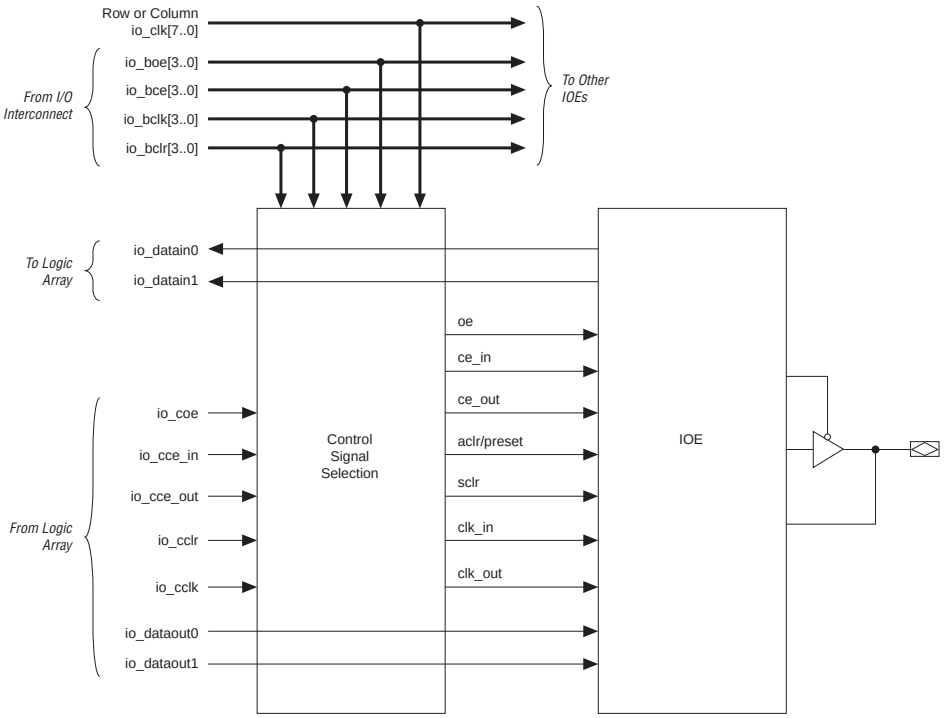
Notes to Figure 4–59:

(1) The 16 control signals are composed of four output enables `io_boe[3..0]`, four clock enables `io_bce[3..0]`, four clocks `io_clk[3..0]`, and four clear signals `io_bclr[3..0]`.

(2) The 28 data and control signals consist of eight data out lines: four lines each for DDR applications `io_dataouta[3..0]` and `io_dataoutb[3..0]`, four output enables `io_coe[3..0]`, four input clock enables `io_cce_in[3..0]`, four output clock enables `io_cce_out[3..0]`, four clocks `io_cclk[3..0]`, and four clear signals `io_cclr[3..0]`.

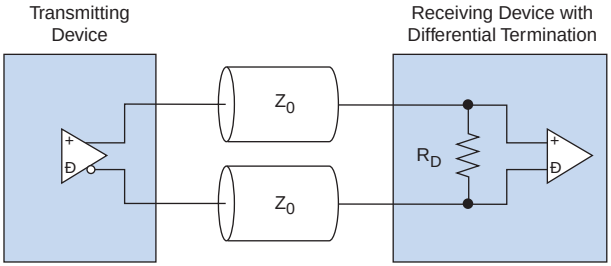
Stratix GX devices have an I/O interconnect similar to the R4 and C4 interconnect to drive high-fanout signals to and from the I/O blocks. There are 16 signals that drive into the I/O blocks composed of four output enables `io_boe[3..0]`, four clock enables `io_bce[3..0]`, four clocks `io_bclk[3..0]`, and four clear signals `io_bclr[3..0]`. The pin's `datain` signals can drive the IO interconnect, which in turn drives the logic array or other I/O blocks. In addition, the control and data signals can be driven from the logic array, providing a slower but more flexible routing resource. The row or column IOE clocks, `io_clk[7..0]`, provide a dedicated routing resource for low-skew, high-speed clocks. I/O clocks are generated from regional, global, or fast regional clocks (see "PLLs & Clock Networks" on page 4–68). Figure 4–61 illustrates the signal paths through the I/O block.

Figure 4–61. Signal Path Through the I/O Block



Each IOE contains its own control signal selection for the following control signals: `oe`, `ce_in`, `ce_out`, `aclr/preset`, `sclr/preset`, `clk_in`, and `clk_out`. Figure 4–62 illustrates the control signal selection.

Figure 4–70. LVDS Input Differential On-Chip Termination



I/O banks on the left and right side of the device support LVDS receiver (far-end) differential termination.

Table 4–29 shows the Stratix GX device differential termination support.

Table 4–29. Differential Termination Supported by I/O Banks

Differential Termination Support	I/O Standard Support	Top & Bottom Banks (3, 4, 7 & 8)	Left Banks (1 & 2)
Differential termination *(1)*, *(2)*	LVDS		✓

Notes to Table 4–29:
(1) Clock pin CLK0, CLK2, CLK9, CLK11, and pins FPLL[7..10]CLK do not support differential termination.
(2) Differential termination is only supported for LVDS because of a 3.3-V V_{CCIO}.

Table 4–30 shows the termination support for different pin types.

Table 4–30. Differential Termination Support Across Pin Types

Pin Type	R_D
Top and bottom I/O banks (3, 4, 7, and 8)	
DIFFIO_RX[]	✓
CLK[0,2,9,11],CLK[4-7],CLK[12-15]	
CLK[1,3,8,10]	✓
FCLK	
FPLL[7..10]CLK	

The differential on-chip resistance at the receiver input buffer is 118 Ω ±20 %.

Partial Reconfiguration

The enhanced PLLs within the Stratix GX device family support partial reconfiguration of their multiply, divide, and time delay settings without reconfiguring the entire device. You can use either serial data from the logic array or regular I/O pins to program the PLL's counter settings in a serial chain. This option provides considerable flexibility for frequency synthesis, allowing real-time variation of the PLL frequency and delay. The rest of the device is functional while reconfiguring the PLL. See the *Stratix GX Architecture* chapter of the *Stratix GX Device Handbook, Volume 1* for more information on Stratix GX PLLs.

Remote Update Configuration Modes

Stratix GX devices also support remote configuration using an Altera enhanced configuration device (for example, EPC16, EPC8, and EPC4 devices) with page mode selection. Factory configuration data is stored in the default page of the configuration device. This is the default configuration which contains the design required to control remote updates and handle or recover from errors. You write the factory configuration once into the flash memory or configuration device. Remote update data can update any of the remaining pages of the configuration device. If there is an error or corruption in a remote update configuration, the configuration device reverts back to the factory configuration information.

There are two remote configuration modes: remote and local configuration. You can use the remote update configuration mode for all three configuration modes: serial, parallel synchronous, and parallel asynchronous. Configuration devices (for example, EPC16 devices) only support serial and parallel synchronous modes. Asynchronous parallel mode allows remote updates when an intelligent host is used to configure the Stratix GX device. This host must support page mode settings similar to an EPC16 device.

Remote Update Mode

When the Stratix GX device is first powered-up in remote update programming mode, it loads the configuration located at page address `000`. The factory configuration should always be located at page address `000`, and should never be remotely updated. The factory configuration contains the required logic to perform the following operations:

- Determine the page address/load location for the next application's configuration data
- Recover from a previous configuration error

Internal Timing Parameters

Internal timing parameters are specified on a speed grade basis independent of device density. Tables 6–36 through 6–42 describe the Stratix GX device internal timing microparameters for LEs, IOEs, TriMatrix™ memory structures, DSP blocks, and MultiTrack interconnects.

Table 6–36. LE Internal Timing Microparameter Descriptions

Symbol	Parameter
t_{SU}	LE register setup time before clock
t_{H}	LE register hold time after clock
t_{CO}	LE register clock-to-output delay
t_{LUT}	LE combinational LUT delay for data-in to data-out
t_{CLR}	Minimum clear pulse width
t_{PRE}	Minimum preset pulse width
t_{CLKHL}	Minimum clock high or low time

Table 6–37. IOE Internal Timing Microparameter Descriptions

Symbol	Parameter
t_{SU}	IOE input and output register setup time before clock
t_{H}	IOE input and output register hold time after clock
t_{CO}	IOE input and output register clock-to-output delay
$t_{PIN2COMBOUT\_R}$	Row input pin to IOE combinational output
$t_{PIN2COMBOUT\_C}$	Column input pin to IOE combinational output
$t_{COMBIN2PIN\_R}$	Row IOE data input to combinational output pin
$t_{COMBIN2PIN\_C}$	Column IOE data input to combinational output pin
t_{CLR}	Minimum clear pulse width
t_{PRE}	Minimum preset pulse width
t_{CLKHL}	Minimum clock high or low time

Tables 6–78 and 6–79 show the adder delays for the column and row IOE programmable delays, respectively. These delays are controlled with the Quartus II software logic options listed in the Parameter column.

Table 6–78. Stratix GX IOE Programmable Delays on Column Pins

Parameter	Setting	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	
Decrease input delay to internal cells	Off		3,970		4,367		5,022	ps
	On		3,390		3,729		4,288	ps
	Small		2,810		3,091		3,554	ps
	Medium		212		224		257	ps
	Large		212		224		257	ps
Decrease input delay to input register	Off		3900		4,290		4,933	ps
	On		0		0		0	ps
Decrease input delay to output register	Off		1,240		1,364		1,568	ps
	On		0		0		0	ps
Increase delay to output pin	Off		0		0		0	ps
	On		377		397		456	ps
Increase delay to output enable pin	Off		0		0		0	ps
	On		338		372		427	ps
Increase output clock enable delay	Off		0		0		0	ps
	On		540		594		683	ps
	Small		1,016		1,118		1,285	ps
	Large		1,016		1,118		1,285	ps
Increase input clock enable delay	Off		0		0		0	ps
	On		540		594		683	ps
	Small		1,016		1,118		1,285	ps
	Large		1,016		1,118		1,285	ps
Increase output enable clock enable delay	Off		0		0		0	ps
	On		540		594		683	ps
	Small		1,016		1,118		1,285	ps
	Large		1,016		1,118		1,285	ps